PCN Number:	20231129002.1	**PCN Date:**	November 30, 2023
Title:	Qualification of RFAB as an additional Fab site option for select HPA07 devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	Feb 29, 2024	**Sample requests accepted until:**	Dec 29, 2023*

***Sample requests received after December 29, 2023 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			New Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**New Fab Site**	**Process**	**Wafer Diameter**
DP1DM5	HPA07	200mm	RFAB	HPA07	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

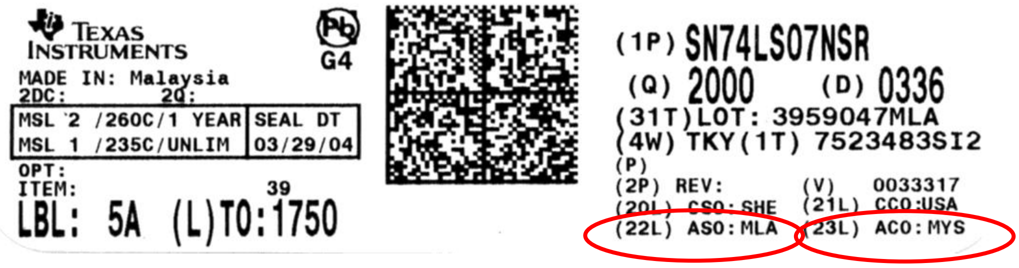
None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label)

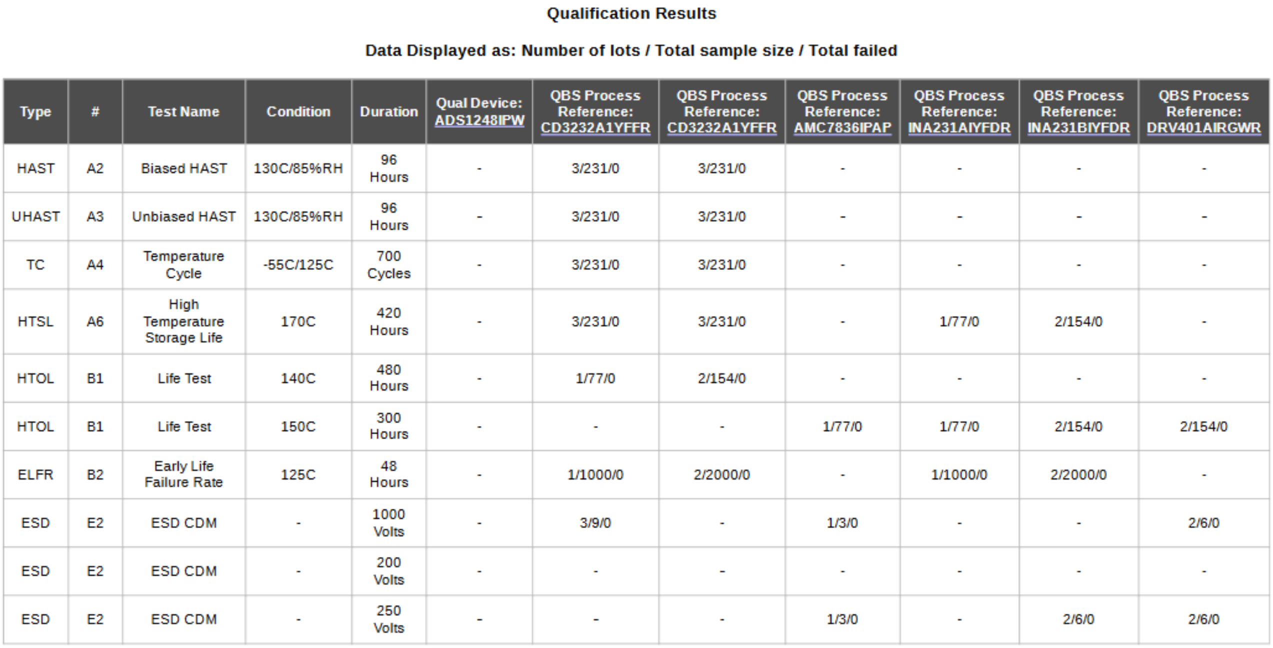


TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO:SHE (21L) CCO:USA
(22L) ASO:MLA (23L) ACO:MYS

Product Affected:

ADS1146IPW	ADS114S06IRHBR	ADS1248IPW	DAC7716SPFB
ADS1146IPWR	ADS114S06IRHBT	ADS1248IPWR	DAC7716SPFBR
ADS1147IPW	ADS114S08BIPBS	ADS124S06BIPBS	DAC7716SRHAR
ADS1147IPWR	ADS114S08BIPBSR	ADS124S06BIPBSR	DAC7716SRHAT

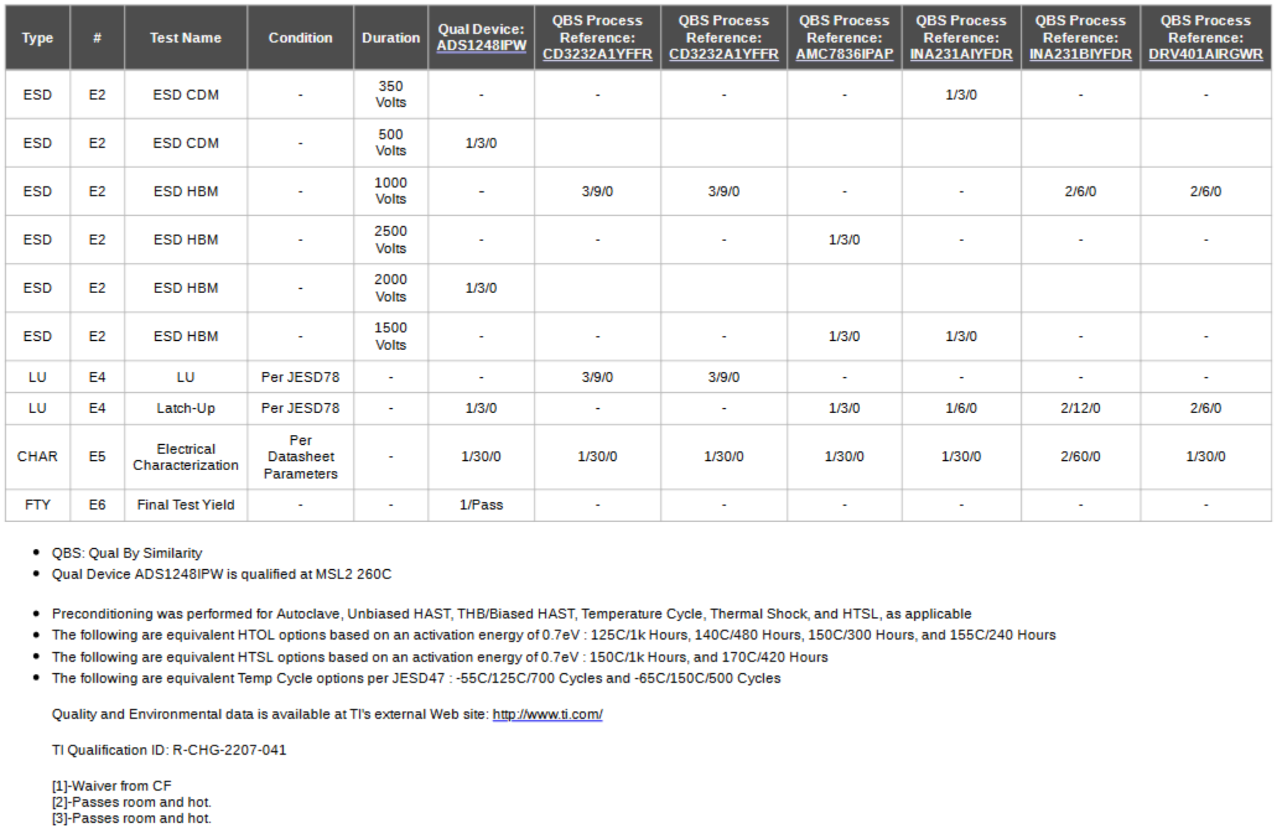
ADS1148IPW	ADS114S08BIRHBR	ADS124S06IPBS	DAC8234SPFB
ADS1148IPWR	ADS114S08BIRHBT	ADS124S06IPBSR	DAC8234SPFBR
ADS1148IRHBR	ADS114S08IPBS	ADS124S06IRHBR	DAC8234SRHAR
ADS1148IRHBT	ADS114S08IPBSR	ADS124S06IRHBT	DAC8234SRHAT
ADS114S06BIPBS	ADS114S08IRHBR	ADS124S08BIPBS	DAC8734SPFB
ADS114S06BIPBSR	ADS114S08IRHBT	ADS124S08BIPBSR	DAC8734SPFBR
ADS114S06BIRHBR	ADS1246IPW	ADS124S08IPBS	DAC8734SRHAR
ADS114S06BIRHBT	ADS1246IPWR	ADS124S08IPBSR	DAC8734SRHAT
ADS114S06IPBS	ADS1247IPW	ADS124S08IRHBR	
ADS114S06IPBSR	ADS1247IPWR	ADS124S08IRHBT	



Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: ADS1248IPW	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: AMC7836IPAP	QBS Process Reference: INA231AIYFDR	QBS Process Reference: INA231BIYFDR	QBS Process Reference: DRV401AIRGWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	3/231/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	-	1/77/0	2/154/0	-
HTOL	B1	Life Test	140C	480 Hours	-	1/77/0	2/154/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	1/77/0	2/154/0	2/154/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	1/1000/0	2/2000/0	-	1/1000/0	2/2000/0	-
ESD	E2	ESD CDM	-	1000 Volts	-	3/9/0	-	1/3/0	-	-	2/6/0
ESD	E2	ESD CDM	-	200 Volts	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0	-	2/6/0	2/6/0



Type	#	Test Name	Condition	Duration	Qual Device: ADS1248IPW	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: AMC7836IPAP	QBS Process Reference: INA231AIYFDR	QBS Process Reference: INA231BIYFDR	QBS Process Reference: DRV401AIRGWR
ESD	E2	ESD CDM	-	350 Volts	-	-	-	-	1/3/0	-	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0						
ESD	E2	ESD HBM	-	1000 Volts	-	3/9/0	3/9/0	-	-	2/6/0	2/6/0
ESD	E2	ESD HBM	-	2500 Volts	-	-	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0						
ESD	E2	ESD HBM	-	1500 Volts	-	-	-	1/3/0	1/3/0	-	-
LU	E4	LU	Per JESD78	-	-	3/9/0	3/9/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	1/3/0	1/6/0	2/12/0	2/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	2/60/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	-	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device ADS1248IPW is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2207-041

[1]-Waiver from CF
[2]-Passes room and hot.
[3]-Passes room and hot.

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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